




PCN Number:	20210831000.1		PCN Date:	September 01, 2021									
Title:	Qualification of TI Malaysia as an additional assembly site for selected devices												
Customer Contact:	PCN Manager	Dept:	Quality Services										
Proposed 1st Ship Date:	Dec 01, 2021	Estimated Sample Availability:	Date provided at sample request										
Change Type:													
<input checked="" type="checkbox"/> Assembly Site	<input type="checkbox"/> Design	<input type="checkbox"/> Wafer Bump Site											
<input type="checkbox"/> Assembly Process	<input type="checkbox"/> Data Sheet	<input type="checkbox"/> Wafer Bump Material											
<input checked="" type="checkbox"/> Assembly Materials	<input type="checkbox"/> Part number change	<input type="checkbox"/> Wafer Bump Process											
<input type="checkbox"/> Mechanical Specification	<input type="checkbox"/> Test Site	<input type="checkbox"/> Wafer Fab Site											
<input type="checkbox"/> Packing/Shipping/Labeling	<input type="checkbox"/> Test Process	<input type="checkbox"/> Wafer Fab Materials											
		<input type="checkbox"/> Wafer Fab Process											
PCN Details													
Description of Change:													
<p>Texas Instruments is pleased to announce the qualification of TI Malaysia as an additional assembly site for devices listed in the Product affected section below. Current assembly sites and differences are as follows:</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th></th> <th>TI Taiwan</th> <th>TI Malaysia</th> </tr> </thead> <tbody> <tr> <td>Mount Compound</td> <td>4042500</td> <td>4147858</td> </tr> <tr> <td>Mold Compound</td> <td>4206193</td> <td>4211471</td> </tr> </tbody> </table>						TI Taiwan	TI Malaysia	Mount Compound	4042500	4147858	Mold Compound	4206193	4211471
	TI Taiwan	TI Malaysia											
Mount Compound	4042500	4147858											
Mold Compound	4206193	4211471											
Reason for Change:													
Continuity of Supply													
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):													
None													
Impact on Environmental Ratings													
Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.													
RoHS	REACH	Green Status	IEC 62474										
<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change	<input checked="" type="checkbox"/> No Change										
Changes to product identification resulting from this PCN:													
Assembly Site	Assembly Site Origin (22L)	Assembly Country Code (23L)	Assembly City										
TI Taiwan	TAI	TWN	Chung Ho, New Taipei City										
TI Malaysia	MLA	MYS	Kuala Lumpur										
Sample product shipping label (not actual product label)													

 TEXAS INSTRUMENTS MADE IN: Malaysia 2DC: 2Q: MSL 2 /260C/1 YEAR SEAL DT MSL 1 /235C/UNLIM 03/29/04 OPT: ITEM: 39 LBL: 5A (L)T0:1750	 G4		(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T) LOT: 3959047MLA (4W) TKY (1T) 7523483SI2 (P) (2P) REV: (V) 0033317 (20L) CSO: SHE (21L) CCO:USA (22L) ASO: MLA (23L) ACO: MYS
Product Affected:			
MSP430FR2000IPW16R	MSP430FR2100IPW16R	MSP430FR2110IPW16R	MSP430FR2111IPW16R

Qualification Report

Approval Date: 04-Mar-2020

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: MSP430FR2522IPW16
AC	Autoclave 121C	96 Hours	3/231/0
HAST	Biased HAST, 130C/85%RH	96 Hours	3/77/0
HTSL	High Temp. Storage Bake, 150C	1000 Hours	3/231/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0
WBP	Bond Pull	Wires	3/228/0
WBS	Ball Bond Shear	Wires	3/228/0

- QBS: Qualification By Similarity
- Qualification Device MSP430FR2522IPW16 is qualified at Moisture Sensitivity LEVEL2-260C.
- Preconditioning was performed for Autoclave, Biased HAST, Temperature Cycle, and HTSL.

Quality and Environmental data is available at TI's external Web site: <http://www.ti.com/Green/Pb-free> Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

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